

## TDFM2A-5775T-10A-02

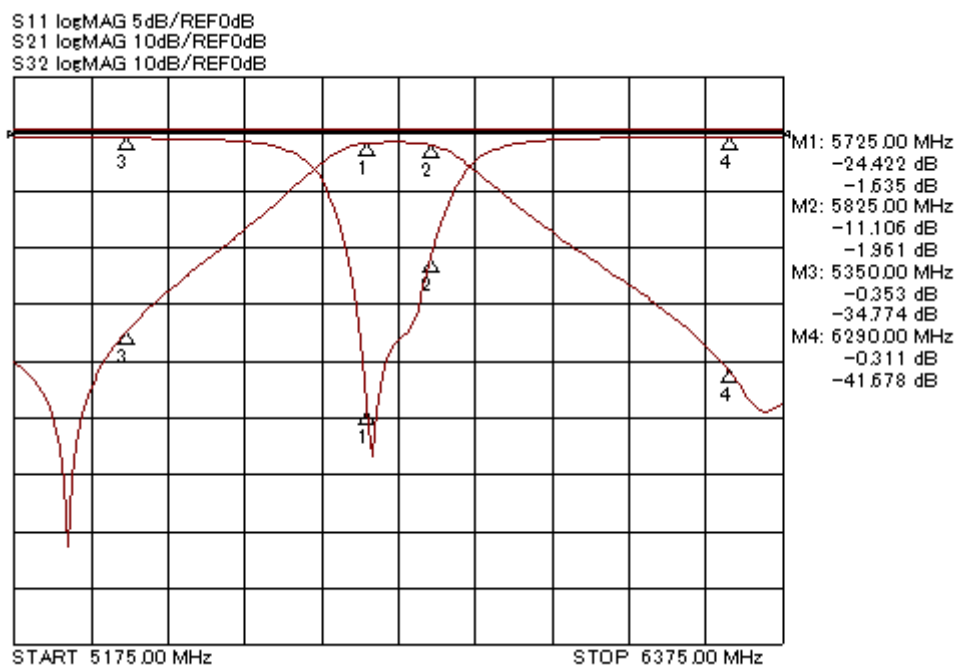
Rev. A

Part Number/Tape & Reel information

| Part Number          | Packaging        | MOQ           |
|----------------------|------------------|---------------|
| TDFM2A-5775T-10A-02P | 330 mm dia. reel | 2000 pcs/reel |

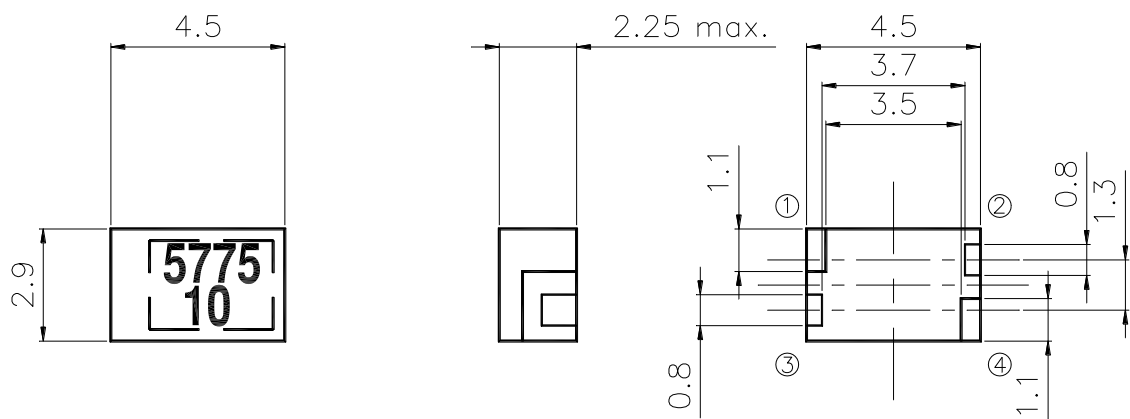
Specifications -40 to +75°C

| Parameter                | IN to OUT                              |
|--------------------------|----------------------------------------|
| Center Frequency         | F0 : 5775 MHz                          |
| Band Width (BW)          | F0 +/- 50 MHz                          |
| Insertion Loss           | 3.4 dB max.                            |
| Ripple at BW             | 1.5 dB max.                            |
| V.S.W.R. at BW           | 2.8 max.                               |
| Input Power              | 1.0 W max.                             |
| Attenuation              | 5350MHz 25dB min.<br>6290MHz 25dB min. |
| Characteristic Impedance | 50 Ohms                                |

Frequency Response

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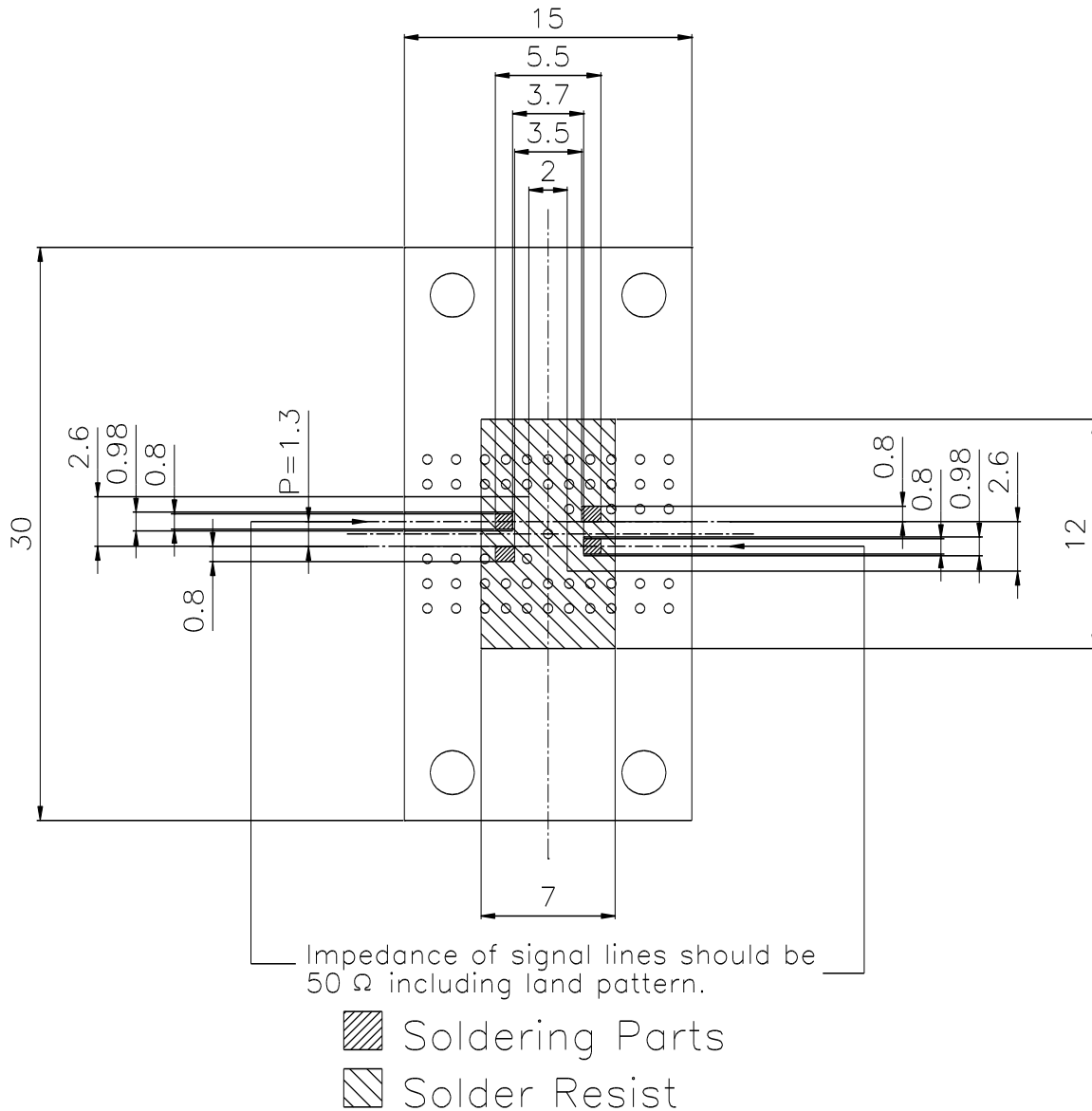
Dimensions and Marking

Tolerance:  $\pm 0.3$   
Unit : mm

|   |     |   |     |
|---|-----|---|-----|
| ① | GND | ② | IN  |
| ③ | OUT | ④ | GND |

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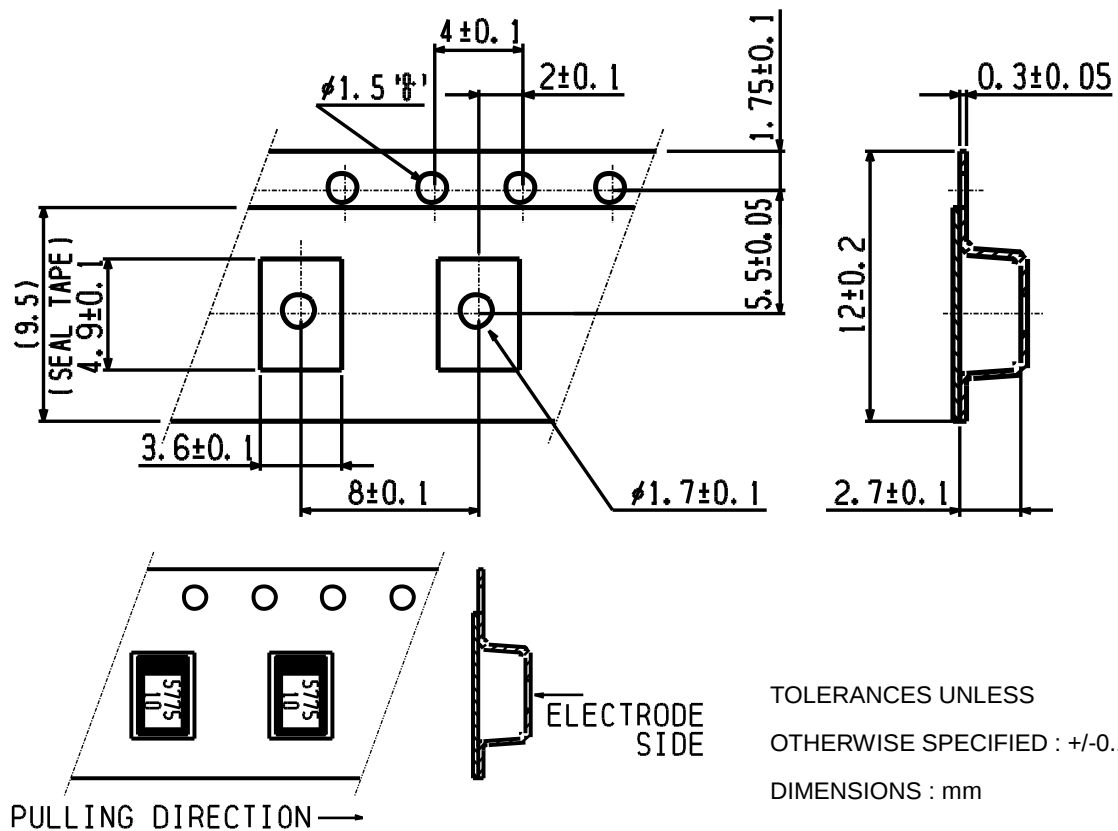
Recommend Land Pattern (reference)

Note : Impedance of signal lines should be 50 ohms including land pattern. This standard condition is applying to the BT resin board (t = 0.4, dielectric constant = 3.6, copper plating on both surfaces).

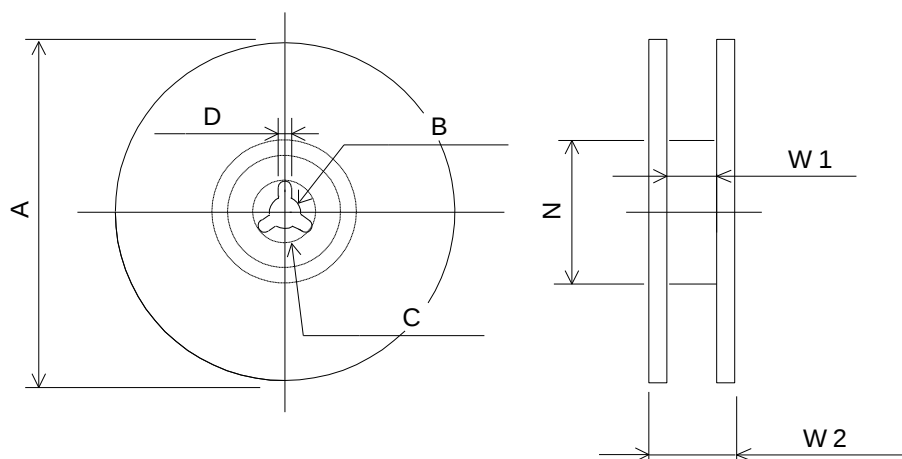
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## Dimensions of Carrier Tape



## Dimensions of Reel



| Murata Part Number   | A+/-2.0 | B+/-0.5 | C+/-1.0 | D+/-0.5 | N (min.) | W1+/-0.5 | W2+/-1.0 |
|----------------------|---------|---------|---------|---------|----------|----------|----------|
| TDFM2A-5775T-10A-02P | φ 330   | φ 13    | φ 21    | 2       | φ 80     | 13.5     | 17.5     |

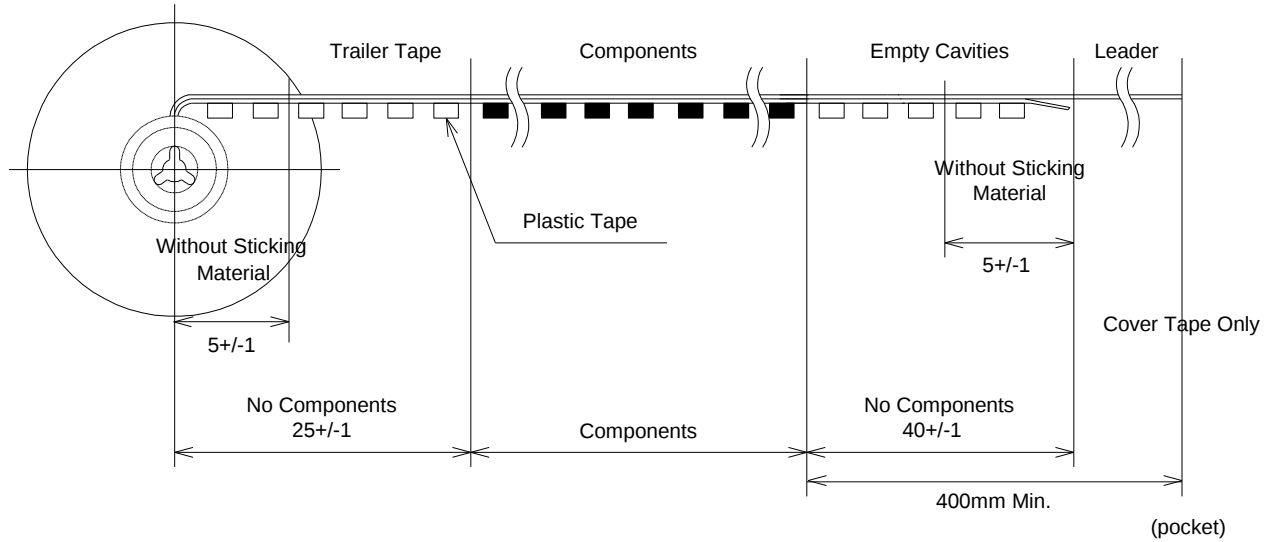
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\*Note: All the technical data and information contained herein are subject to change without advanced notice.

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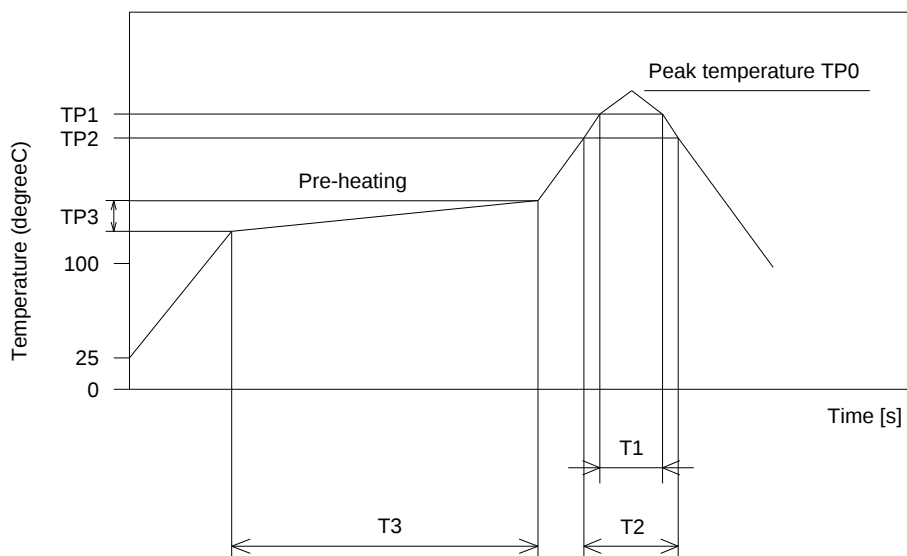
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## Taping Condition



## TDFM2A-5775T-10A-02

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Reflow Soldering Standard Conditions

Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

|                                          |                     | TP0 (°C ) | TP1 (°C ) | T1 (s)  | TP2 (°C ) | T2 (s)   | TP3 (°C )  | T3 (s)    |
|------------------------------------------|---------------------|-----------|-----------|---------|-----------|----------|------------|-----------|
| Reflow standard condition                | Sn-40Pb solder      | 235+/-5   | 230       | 10 max. | 200       | 45 to 55 | 70 to 130  | 70 to 130 |
|                                          | Sn-3Ag-0.5Cu solder | 255+/-5   | 250       | 10 max. | 220       | 20 to 40 | 150 to 190 | 60 to 120 |
| Test condition of reflow heat resistance |                     | 255+/-5   | 250       | 10 max. | 220       | 20 to 40 | 150 to 190 | 60 to 120 |

Reflow soldering is available 2 times for above test condition of reflow heat resistance.